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(12) **United States Design Patent**  
**Adams et al.**

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(54) **CONTACT FIELD FOR A PRINTED CIRCUIT BOARD**

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(\*\*) Term: **14 Years**

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(52) **U.S. Cl.**  
USPC ..... **D13/182**

(58) **Field of Classification Search**  
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H05K 2201/10659; H05K 2201/10689;  
H05K 2201/10719; H05K 7/1084; H05K  
3/222; H05K 3/325; H05K 1/00; H05K  
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Y10T 29/49147; Y10T 29/49149; Y10T  
29/49156

See application file for complete search history.

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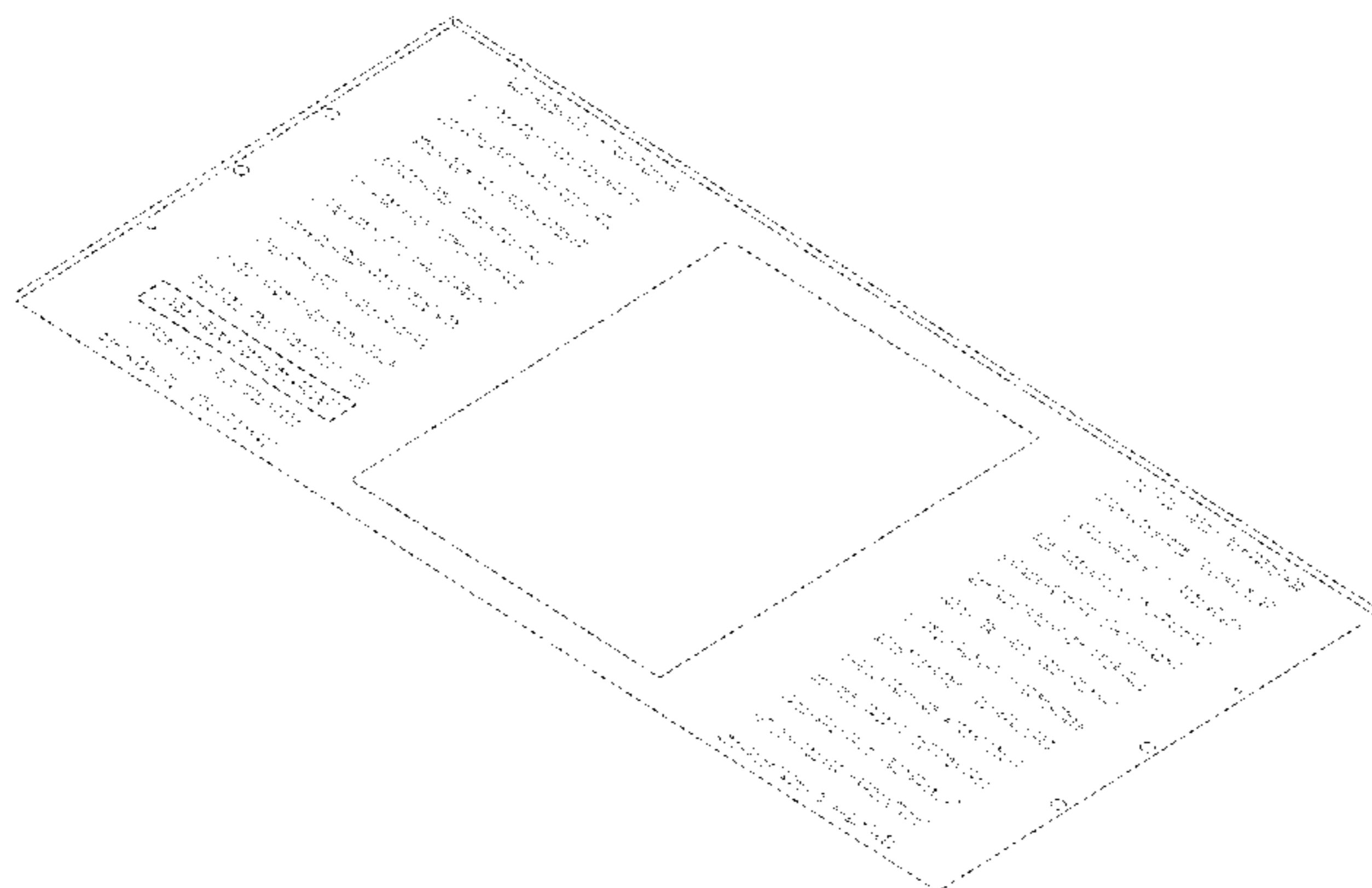
(57) **CLAIM**

The ornamental design for a contact field for a printed circuit board, substantially as shown and described.

**DESCRIPTION**

FIG. 1 is a top perspective view of a contact field for a printed circuit board;  
FIG. 2 is a bottom perspective view thereof;  
FIG. 3 is a right side elevation view thereof;  
FIG. 4 is a left side elevation view thereof;  
FIG. 5 is a front elevation view thereof;  
FIG. 6 is a rear elevation view thereof;  
FIG. 7 is a top plan view thereof;  
FIG. 8 is a bottom plan view thereof;  
FIG. 9 is a first close up bottom plan view thereof; and,  
FIG. 10 is a second close up bottom plan view thereof.  
The broken lines shown represent portions of the contact field for a printed circuit board that form no part of the claimed design.

**1 Claim, 8 Drawing Sheets**



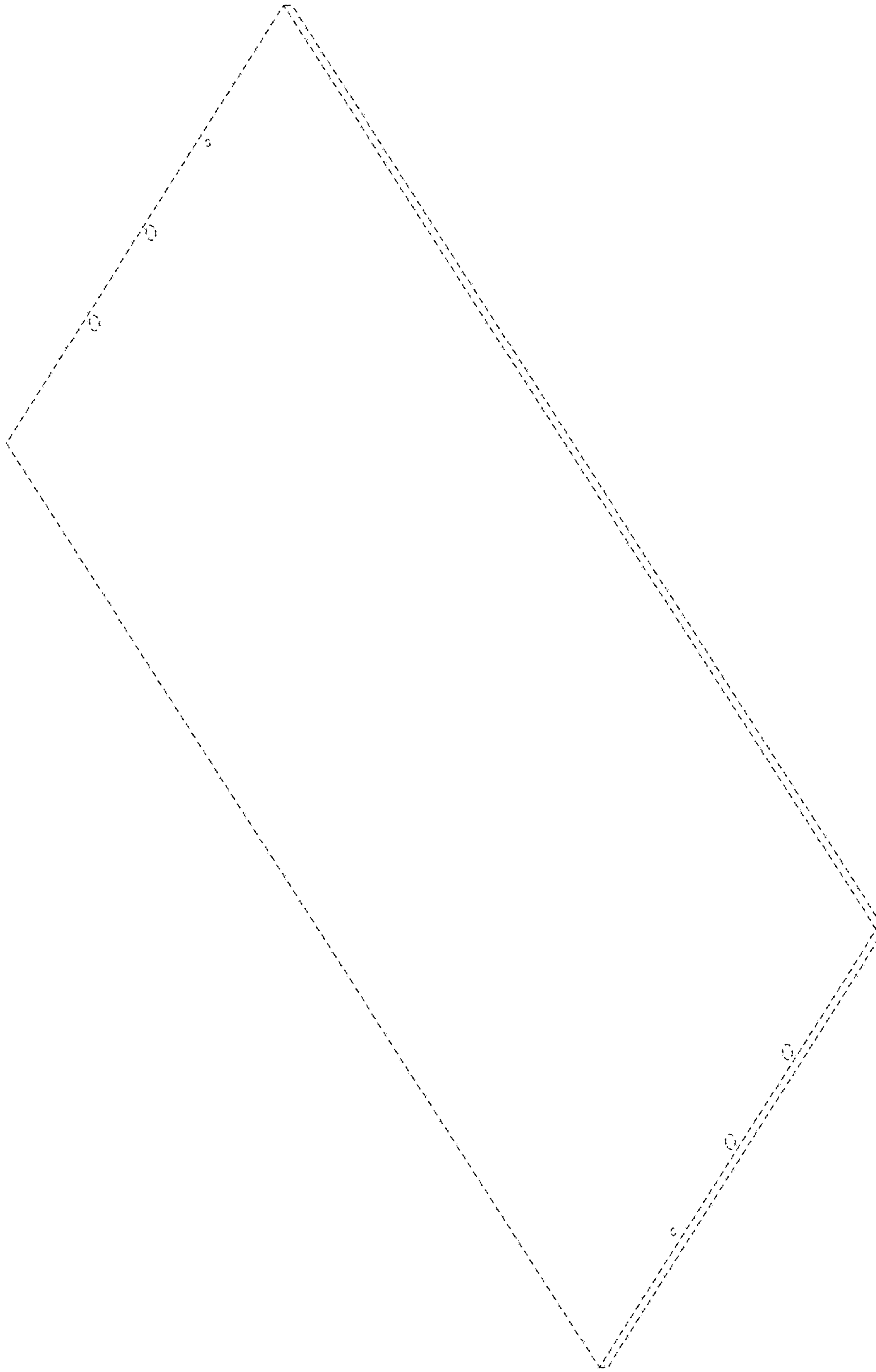


FIG. 1

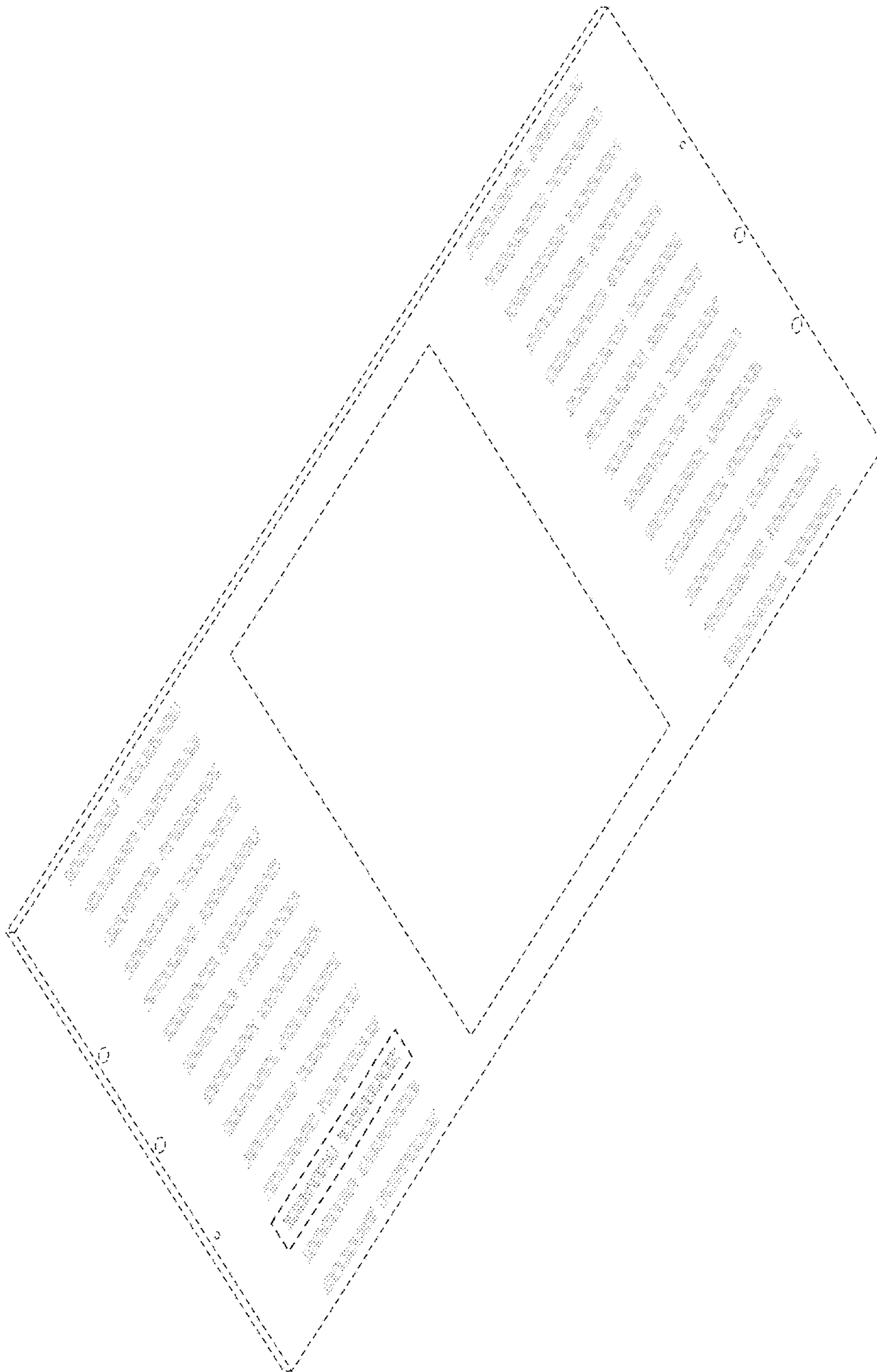
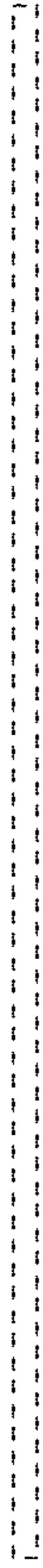
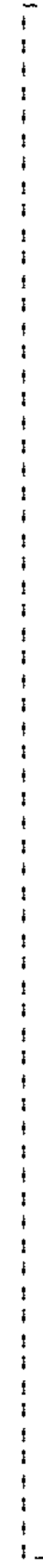


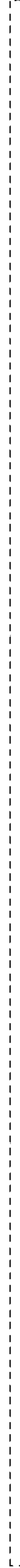
FIG. 2



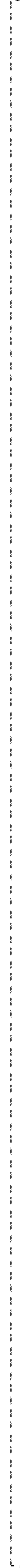
**FIG. 3**



**FIG. 4**



**FIG. 5**



**FIG. 6**



FIG. 7

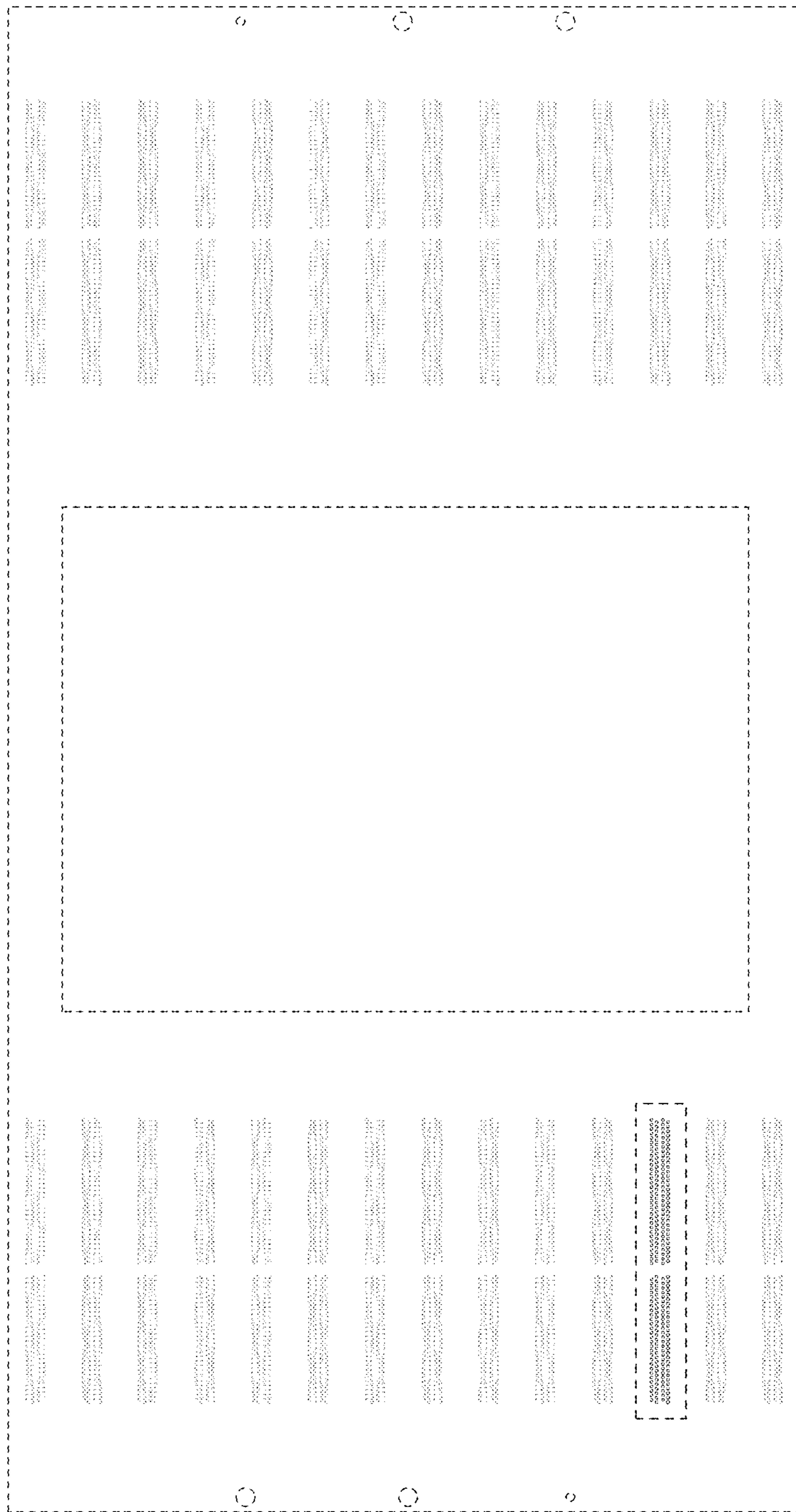
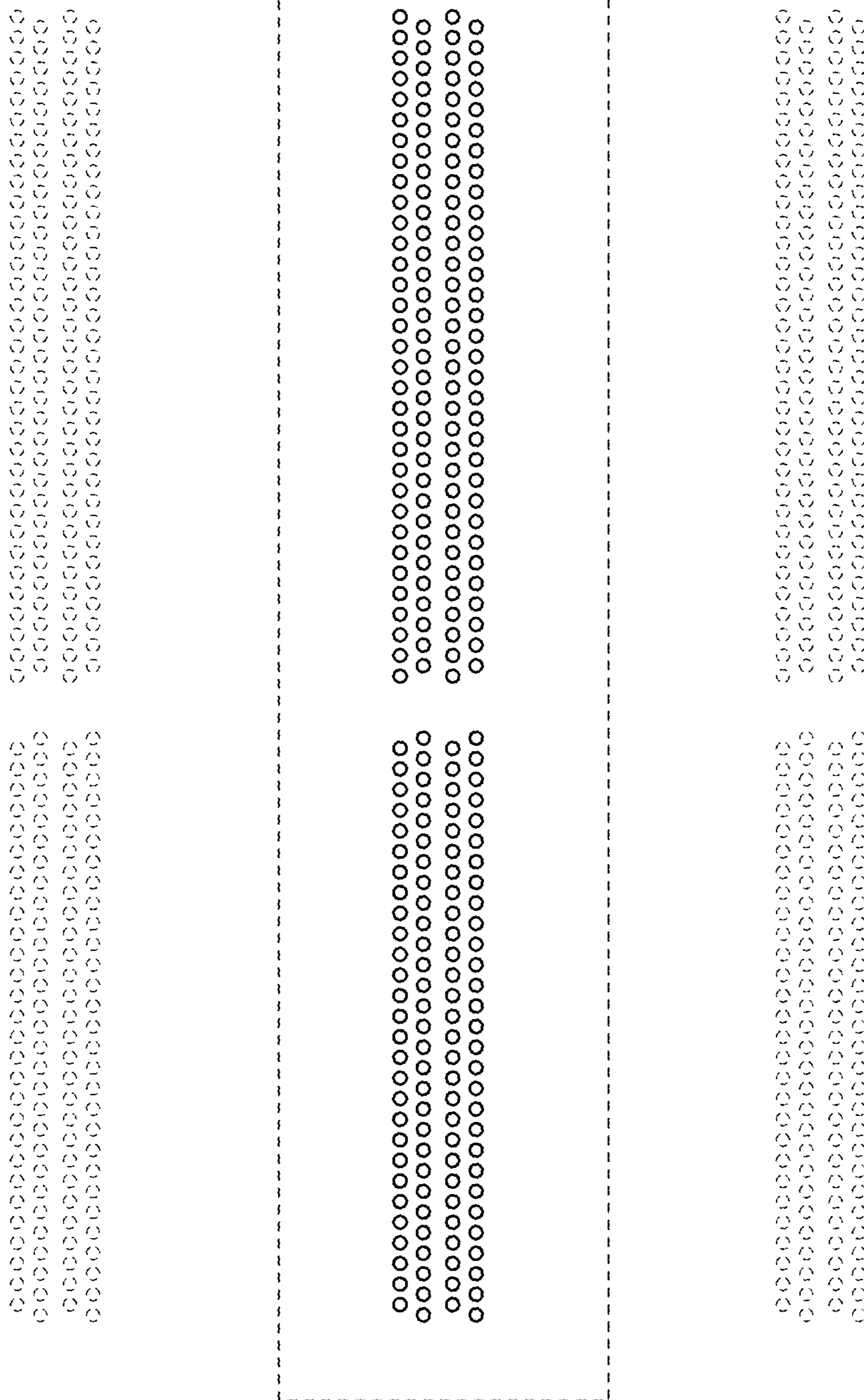


FIG. 8



**FIG. 9**



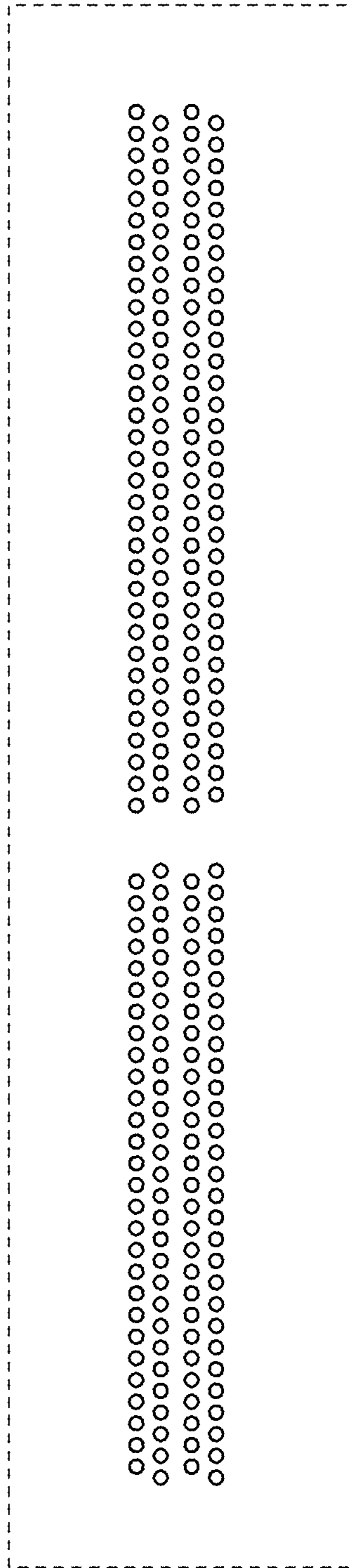


FIG. 10